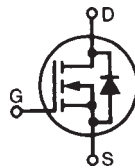


## Polar™ Power MOSFET HiPerFET™

N-Channel Enhancement Mode  
Avalanche Rated  
Fast Intrinsic Diode

**IXFH12N120P**  
**IXFV12N120P**  
**IXFV12N120PS**

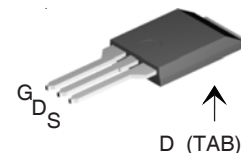


Symbol	Test Conditions	Maximum Ratings	
$V_{DSS}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	1200	V
$V_{DGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ , $R_{GS} = 1\text{M}\Omega$	1200	V
$V_{GSS}$	Continuous	$\pm 30$	V
$V_{GSM}$	Transient	$\pm 40$	V
$I_{D25}$	$T_C = 25^\circ\text{C}$	12	A
$I_{DM}$	$T_C = 25^\circ\text{C}$ , pulse width limited by $T_{JM}$	30	A
$I_A$	$T_C = 25^\circ\text{C}$	6	A
$E_{AS}$	$T_C = 25^\circ\text{C}$	500	mJ
$dV/dt$	$I_S \leq I_{DM}$ , $V_{DD} \leq V_{DSS}$ , $T_J \leq 150^\circ\text{C}$	15	V/ns
$P_D$	$T_C = 25^\circ\text{C}$	543	W
$T_J$		-55 ... +150	$^\circ\text{C}$
$T_{JM}$		150	$^\circ\text{C}$
$T_{stg}$		-55 ... +150	$^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering	300	$^\circ\text{C}$
$T_{SOLD}$	Plastic body for 10s	260	$^\circ\text{C}$
$M_d$	Mounting torque (TO-247)	1.13/10	Nm/lb.in.
$F_C$	Mounting force (PLUS 220)	11..65 / 2.5..14.6	N/lb.
Weight	TO-247	6	g
	PLUS 220 types	4	g

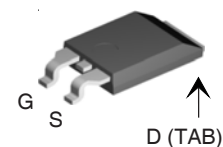
Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
$BV_{DSS}$	$V_{GS} = 0\text{V}$ , $I_D = 1\text{mA}$	1200		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 1\text{mA}$	3.5		6.5 V
$I_{GSS}$	$V_{GS} = \pm 30\text{V}$ , $V_{DS} = 0\text{V}$			$\pm 100$ nA
$I_{DSS}$	$V_{DS} = V_{DSS}$			25 $\mu\text{A}$
	$V_{GS} = 0\text{V}$ , $T_J = 125^\circ\text{C}$			2 mA
$R_{DS(on)}$	$V_{GS} = 10\text{V}$ , $I_D = 0.5 \cdot I_{D25}$ , Note 1	1.15	1.35	$\Omega$

$$\begin{aligned} V_{DSS} &= 1200\text{V} \\ I_{D25} &= 12\text{A} \\ R_{DS(on)} &\leq 1.35\Omega \\ t_{rr} &\leq 300\text{ns} \end{aligned}$$

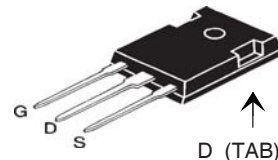
PLUS220 (IXFV)



PLUS220SMD (IXFV\_S)



TO-247 (IXFH)



G = Gate    D = Drain  
S = Source    TAB = Drain

### Features

- International standard packages
- Fast recovery diode
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
  - easy to drive and to protect

### Advantages

- Easy to mount
- Space savings
- High power density

### Applications:

- High Voltage Switched-mode and resonant-mode power supplies
- High Voltage Pulse Power Applications
- High Voltage Discharge circuits in Lasers Pulsers, Spark Igniters, RF Generators
- High Voltage DC-DC converters
- High Voltage DC-AC inverters



Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
$g_{fs}$	$V_{DS} = 20\text{V}, I_D = 0.5 \cdot I_{D25}$ , Note 1	5	9	S
$C_{iss}$	$V_{GS} = 0\text{V}, V_{DS} = 25\text{V}, f = 1\text{MHz}$		5400	pF
$C_{oss}$			290	pF
$C_{rss}$			40	pF
$R_{Gi}$	Gate input resistance		1.5	$\Omega$
$t_{d(on)}$	<b>Resistive Switching Times</b> $V_{GS} = 10\text{V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$ $R_G = 2\Omega$ (External)		34	ns
$t_r$			25	ns
$t_{d(off)}$			62	ns
$t_f$			34	ns
$Q_{g(on)}$	$V_{GS} = 10\text{V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$		103	nC
$Q_{gs}$			29	nC
$Q_{gd}$			41	nC
$R_{thJC}$	(TO-247, PLUS 220)			0.23 $^\circ\text{C/W}$
$R_{thCS}$		0.21		$^\circ\text{C/W}$

Source-Drain Diode		Characteristic Values		
$T_J = 25^\circ\text{C}$ unless otherwise specified)		Min.	Typ.	Max.
$I_S$	$V_{GS} = 0\text{V}$			12 A
$I_{SM}$	Repetitive, pulse width limited by $T_{JM}$			48 A
$V_{SD}$	$I_F = I_S, V_{GS} = 0\text{V}$ , Note 1			1.5 V
$t_{rr}$	$I_F = 6\text{A}, -di/dt = 100\text{A}/\mu\text{s}$ $V_R = 100\text{V}, V_{GS} = 0\text{V}$			300 ns
$Q_{RM}$			0.5	$\mu\text{C}$
$I_{RM}$			6	A

Note 1: Pulse test,  $t \leq 300\mu\text{s}$ ; duty cycle,  $d \leq 2\%$ .

# PLUS220SMD (IXFV\_S) Outline

Top view diagram of the PLUS220SMD (IXFV\_S) package. Dimensions shown include E (total width), E1 (width of the central pad), L2 (width of the side pads), D (total length), D1 (length of the central pad), L3 (length of the side pads), L4 (length of the mounting tabs), and 2X b (width of the mounting tabs).

Bottom view diagram of the PLUS220SMD (IXFV\_S) package, showing the four pins: Gate, Drain, Source, and Drain.

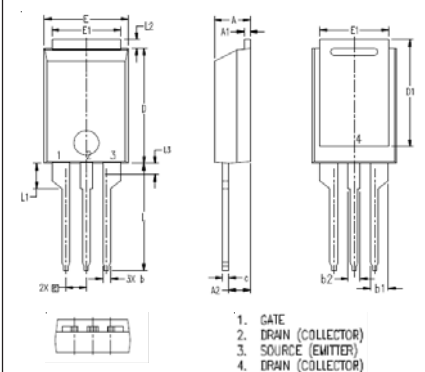
Side view diagram of the PLUS220SMD (IXFV\_S) package. Dimensions shown include A (total height), A1 (height of the central pad), A3 (height of the side pads), L4 (length of the mounting tabs), and A2 (width of the mounting tabs).

Front view diagram of the PLUS220SMD (IXFV\_S) package. Dimensions shown include C1 (width of the central pad), D1 (length of the central pad), H (height of the central pad), L1 (width of the side pads), L2 (width of the side pads), L3 (width of the side pads), and L4 (width of the mounting tabs).

1. GATE
2. DRAIN (COLLECTOR)
3. SOURCE (EMITTER)
4. DRAIN (COLLECTOR)

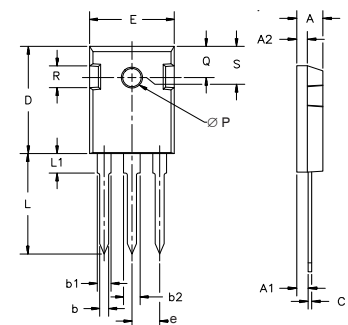
SYM	INCHES		MILLIMETER	
	MIN	MAX	MIN	MAX
A	.169	.185	4.30	4.70
A1	.028	.035	0.70	0.90
A2	.098	.118	2.50	3.00
A3	.000	.010	0.00	0.25
b	.035	.047	0.90	1.20
b1	.080	.095	2.03	2.41
b2	.054	.064	1.37	1.63
c	.028	.035	0.70	0.90
D	.551	.591	14.00	15.00
D1	.512	.539	13.00	13.70
E	.394	.433	10.00	11.00
E1	.331	.346	8.40	8.80
e	.200BSC 5.08 BSC			
L	.209	.228	5.30	5.80
L1	.118	.138	3.00	3.50
L2	.035	.051	0.90	1.30
L3	.047	.059	1.20	1.50
L4	.039	.059	1.00	1.50

### PLUS220 (IXFV) Outline



SYM	INCHES		MILLIMETER	
	MIN	MAX	MIN	MAX
A	.169	.185	4.30	4.70
A1	.028	.035	0.70	0.90
A2	.098	.118	2.50	3.00
b	.035	.047	0.90	1.20
b1	.080	.095	2.03	2.41
b2	.054	.064	1.37	1.63
c	.028	.035	0.70	0.90
D	.551	.591	14.00	15.00
D1	.512	.539	13.00	13.70
E	.394	.433	10.00	11.00
E1	.331	.346	8.40	8.80
e	.100BSC 2.54 BSC			
L	.512	.551	13.00	14.00
L1	.118	.138	3.00	3.50
L2	.035	.051	0.90	1.30
L3	.047	.059	1.20	1.50

### TO-247 (IXFH) Outline



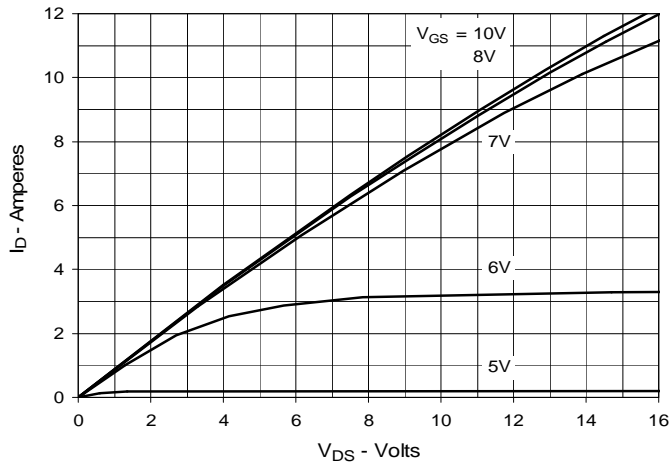
Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.7	5.3	.185	.209
A1	2.2	2.54	.087	.102
A2	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b1	1.65	2.13	.065	.084
b2	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L1		4.50		.177
ØP	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15	BSC	242	BSC

IXYS reserves the right to change limits, test conditions, and dimensions.

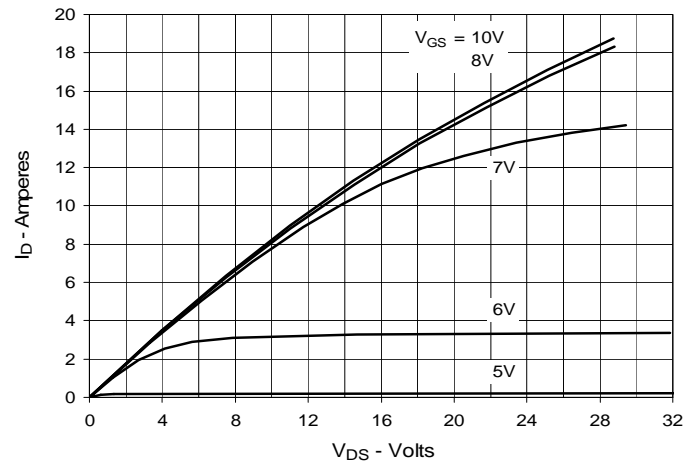
IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:	4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338 B2
	4,850,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
	4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	



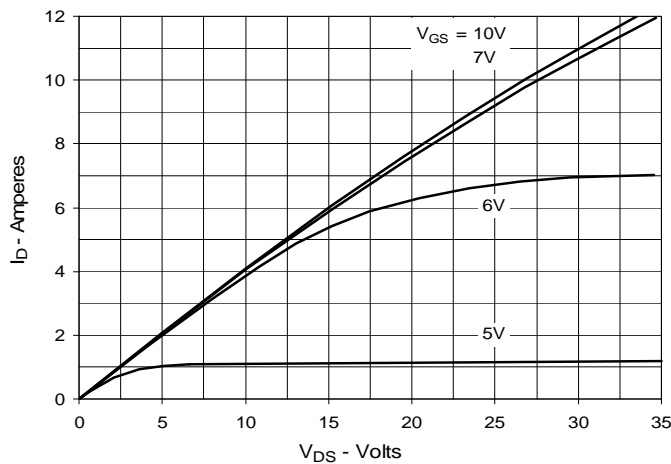
**Fig. 1. Output Characteristics  
@ 25°C**



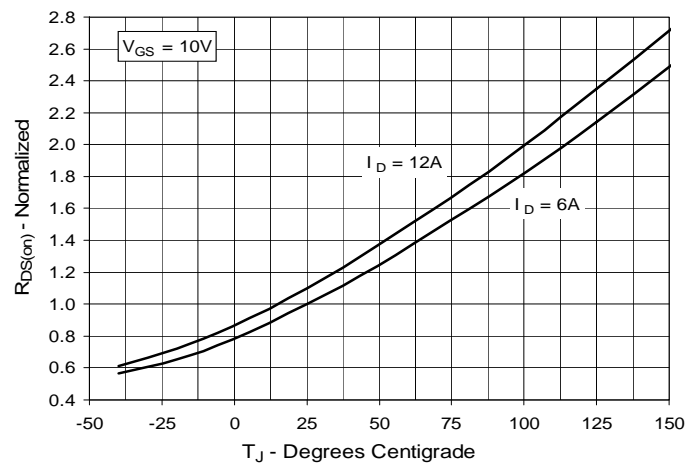
**Fig. 2. Extended Output Characteristics  
@ 25°C**



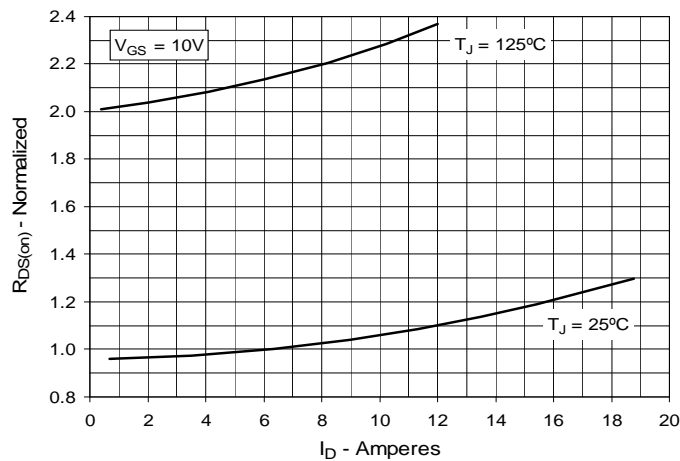
**Fig. 3. Output Characteristics  
@ 125°C**



**Fig. 4.  $R_{DS(on)}$  Normalized to  $I_D = 6A$  Value  
vs. Junction Temperature**



**Fig. 5.  $R_{DS(on)}$  Normalized to  $I_D = 6A$  Value  
vs. Drain Current**



**Fig. 6. Maximum Drain Current vs.  
Case Temperature**

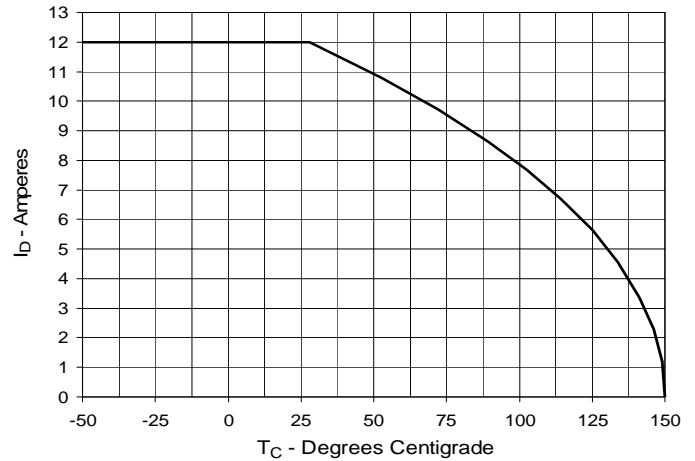




Fig. 7. Input Admittance

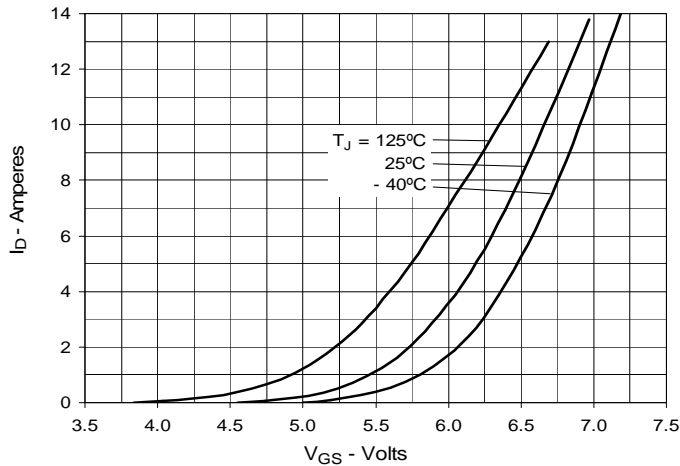


Fig. 8. Transconductance

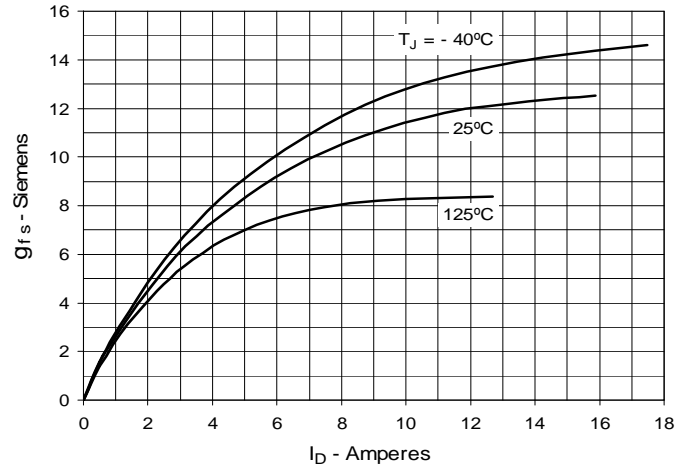


Fig. 9. Forward Voltage Drop of Intrinsic Diode

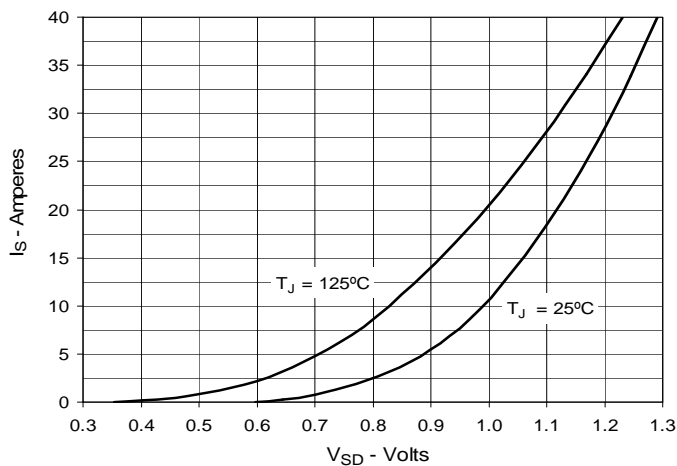


Fig. 10. Gate Charge

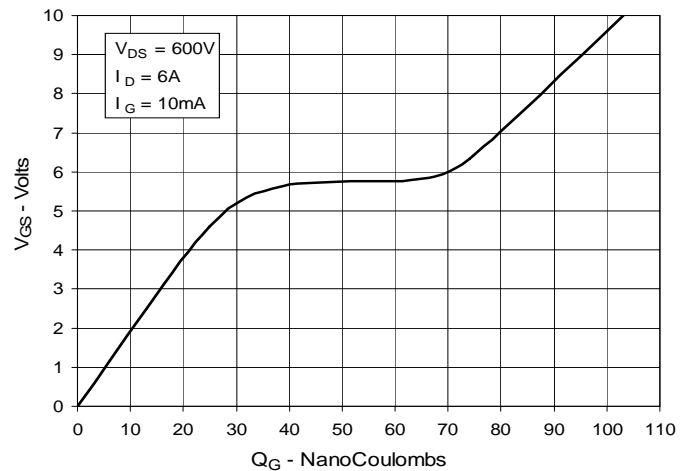


Fig. 11. Capacitance

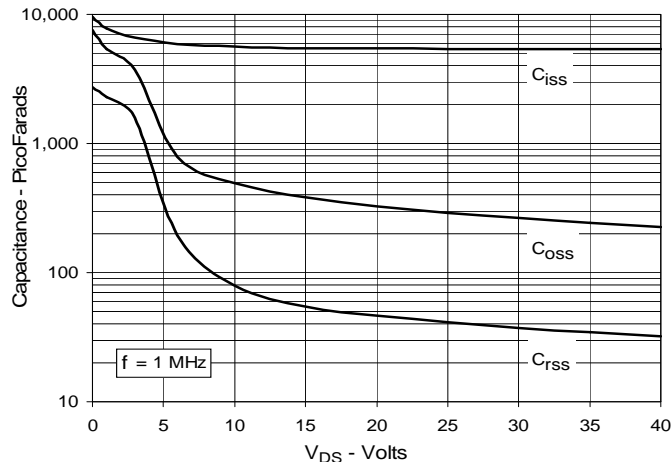
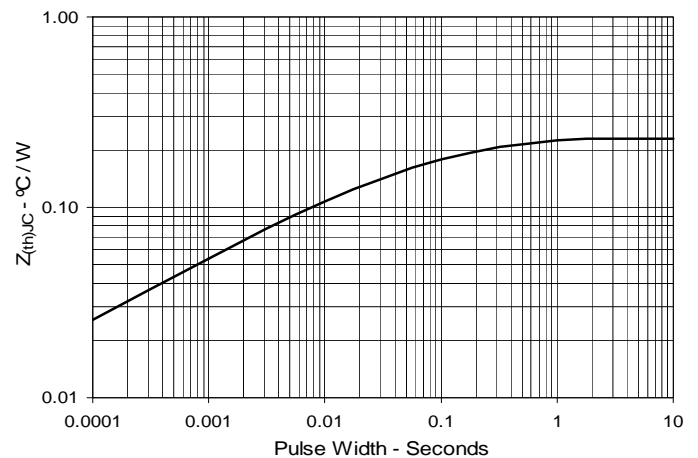


Fig. 12. Maximum Transient Thermal Impedance







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